

**REMARKS**

Claims 1 through 20 are currently pending in the application.

This amendment is in response to the Office Action of November 19, 2002.

Applicants note the filing of an Information Disclosure Statement herein on March 6, 2002, but note that a copy sheet 1 of 3 of Form PTO-1449 was not returned with the outstanding Office Action. Applicants respectfully request that the information cited on sheet 1 of Form PTO-1449 be made of record herein. A copy of page 1 is enclosed herewith for Examiner's reference.

Claims 1 through 20 are rejected under 35 U.S.C. § 101 as claiming the same invention of claims 1 through 20 of United States Patent 6,306,687 (hereinafter referred to as the '687 patent).

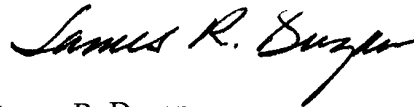
Applicants submit that a reliable test for statutory double patenting under 35 U.S.C. § 101 is whether a claim in the application can be literally infringed without literally infringing a corresponding claim in the patent. Is there an embodiment of the invention that falls within the scope of one claim but not the other: If there is such an embodiment, then identical subject matter is not defined by both claims and statutory double patenting under 35 U.S.C. § 101 does not exist. *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970).

Applicants submit that the embodiments of the inventions set forth in presently amended independent claims 1 and 10 of the present application each clearly claim an embodiment of the invention having an element of the invention calling for "providing a lead frame having a plurality of lead fingers in strip form having a pair of side rails connecting each lead frame to another lead frame in the strip . . . ." whereas neither embodiment of the invention set forth in claims 1 and 10 contains such an element of the invention. Accordingly, no statutory double patenting under 35 U.S.C. § 101 exists. Therefore, claims 1 through 10 are allowable.

**Serial No. 10/092,332**

Applicants request the allowance of claims 1 through 20 and the case passed for issue.

Respectfully submitted,



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Enclosure: Version with Markings to Show Changes Made

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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

IN THE SPECIFICATION:

Please amend the title of the invention as follows:

[TAPE UNDER FRAME FOR CONVENTIONAL-TYPE IC PACKAGE ASSEMBLY]  
METHOD OF FABRICATING A TAPE HAVING APERTURES UNDER A  
LEAD FRAME FOR CONVENTIONAL IC PACKAGES

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

IN THE CLAIMS:

A marked-up version of each of the presently amended claims, highlighting the changes thereto, follows:

1. (Twice Amended) A method of assembling a semiconductor device and a lead frame comprising:  
[forming] providing a lead frame having a plurality of lead fingers in strip form having a pair of side rails connecting each lead frame to another lead frame in the strip, each lead finger of the plurality of lead fingers having a bonding end, the plurality of lead fingers forming an opening at least a size of an attachment surface of a semiconductor device, the lead frame having no die paddle for supporting the semiconductor device thereon;  
forming a segment of tape having a shape to fit over at least the bonding end of each lead finger of the plurality of lead fingers of the lead frame forming the opening, the segment of tape extending between the plurality of lead fingers across the opening, the segment of tape having a thermosetting adhesive located in a portion thereof;  
adhesively attaching the segment of tape to at least the bonding end of each lead finger of the plurality of lead fingers of the lead frame, the segment of tape providing an attachment location for the semiconductor device through use of the thermosetting adhesive; and  
adhesively attaching the semiconductor device to at least a portion of the segment of tape at the attachment location for the semiconductor device using the thermosetting adhesive located on a portion of the segment of tape, the semiconductor device having a portion thereof located within the opening formed by the plurality of lead fingers of the lead frame.

10. (Twice Amended) A method of assembling a semiconductor device and a lead frame comprising:  
[forming] providing a lead frame having a plurality of lead fingers in strip form having a pair of side rails connecting each lead frame to another in the strip, each lead finger of the plurality of lead fingers having an end forming an opening between the ends of the plurality of lead fingers of the lead frame having a size of one of at least a size of an attachment surface of a semiconductor device and greater than the attachment surface of the semiconductor device;  
forming at least two tape segments shaped to fit over a portion of the ends of the plurality of lead fingers of the lead frame, the at least two tape segments extending across the opening having a size of one of at least the size of the attachment surface of the semiconductor device and greater than the attachment surface of the semiconductor device; and  
adhesively attaching the at least two tape segments to the portion of the ends of the plurality of lead fingers, the at least two tape segments being spaced to define at least one opening between the at least two tape segments providing an attachment location for the semiconductor device therein.